

**Amended Claims**

Please replace the pending claims with those listed below, which supercedes all prior versions and listings of claims:

1. (presently amended) A circuit board assembly comprising

a circuit board comprising a substrate and one or more circuit components thereon,

a cover coupled to the circuit board and disposed adjacent to the substrate so as to define a plenum in which one or more of said components are disposed and through which air flows to cool at least one of those components,

said plenum having at least a first edge, for intake of that air flow, disposed between the cover and the substrate at a first edge of at least one of the cover and the substrate,

said plenum having at least a second edge, for exit of that air flow, disposed between the cover and the substrate at a second edge of at least one of the cover and the substrate,

the cover comprising

a planar member and

one or more structural elements coupled to the planar member that regulate any of shock and vibration in any of the cover and the circuit board.

2. (original) The circuit board assembly of claim 1, wherein one or more of the structural elements are formed integrally with the planar member.

3. (original) The circuit board assembly of claim 2, wherein the one or more of the structural elements disposed on a surface of the planar member.

4. (original) The circuit board assembly of claim 1, wherein one or more of the structural elements comprise an elongate member.

5. (original) The circuit board assembly of claim 5, wherein one or more of the structural elements comprise a rod-like member.
6. (original) The circuit board assembly of claim 5, wherein one or more of the structural elements are disposed at one or more ends of the planar member.
7. (original) The circuit board assembly of claim 5, wherein one or more of the structural elements comprise a cross-shaped member.
8. (original) The circuit board assembly of claim 1, wherein one or more of the structural elements comprise a heat-dissipative element.
9. (original) The circuit board assembly of claim 1, wherein one or more of the structural elements are arranged to control electromagnetic emissions.
10. (presently amended) The circuit board assembly of claim 7, wherein one or more of the heat dissipative elements are mounted by one or more springs or other resilient elements (collectively, "springs") to the planar member and in thermal contact with one or more of the circuit components.
11. (presently amended) A cover for use with a circuit board, the cover comprising

a planar member that is mounted adjacent to the circuit board so as to define a plenum in which one or more circuit components are disposed and through which air flows to cool at least one of those components.

said plenum having at least a first edge, for intake of that air flow, disposed between the circuit board and the planar member at a first edge of at least one of the circuit board and the planar member,

said plenum having at least a second edge, for exit of that air flow, disposed between the circuit board and the planar member at a second edge of at least one of the circuit board and the planar member, and

one or more structural elements coupled to the elongate member that regulate shock and vibration in any of the cover and the circuit board.

12. (original) The cover of claim 11, wherein one or more of the structural members comprise an elongate member, a rod-like member, a cross-shaped member and heat-dissipative element.
13. (original) The cover of claim 12, wherein the structural members are disposed on the surface of the planar member.
14. (original) The cover of claim 12, wherein one or more of the structural members are disposed at one or more ends of the planar member.
15. (original) The cover of claim 12, wherein the cover is adapted to be removably affixed to the circuit board.
16. (original) The cover of claim 12, wherein the planar member is thermally conductive.
17. (original) The cover of claim 12, wherein the planar member comprises a cold plate.
18. (original) The circuit board assembly of claim 11, wherein one or more of the structural elements are arranged to control electromagnetic emissions.
19. (presently amended) A circuit board assembly with thermal, shock, vibration, and/or electromagnetic compatibility control, comprising
  - a circuit board comprising a substrate and one or more circuit components thereon,
  - a cover coupled to the circuit board,
  - the cover comprising
    - a heat conductive planar member,
    - one or more a heat-dissipative elements coupled to the planar member, and
    - one or more elongate members disposed on a surface of the planar member

the cover being disposed adjacent to the substrate so as to define a plenum in which one or more of said circuit components are disposed and through which air flows to cool at least one of those components

said plenum having at least a first edge, for intake of that air flow, disposed between the circuit board and the planar member at a first edge of at least one of the circuit board and the planar member,

said plenum having at least a second edge, for exit of that air flow, disposed between the circuit board and the planar member at a second edge of at least one of the circuit board and the planar member, .

20. (presently amended) The circuit board assembly of claim 19, wherein one or more of the heat dissipative elements are mounted by one or more springs or other resilient elements (collectively, "springs") to the planar member and in thermal contact with one or more of the circuit components.
21. (original) The circuit board assembly of claim 19, wherein one or more of the elongate members are disposed at one or more ends of the planar member.
22. (original) The circuit board assembly of claim 21, wherein one or more of the structural elements are arranged to control electromagnetic emissions.